

General Description

The SRE160N065FSUD8 is a Field Stop Trench IGBT with anti-parallel diode, which offers ultra low conduction loss, high energy efficiency for switching applications such as Inverter, Driver, Converter, etc.

The SRE160N065FSUD8 package is TO-247Plus.

Features

- High Breakdown Voltage to 650V
- Advanced Trench Fieldstop technology
 - Short circuit ruggedness > 8us @ 25°C
 - High Ruggedness, Temperature Stability
 - Easy Parallel Switching Capability due to Positive Temperature Coefficient in $V_{CE(SAT)}$
- Low $V_{CE(SAT)}$
- Enhanced Avalanche Capability
- Qualified according to AEC Q101

Application

- Motor Drives
- Inverter & Solar
- Converter with high switching frequency

Symbol

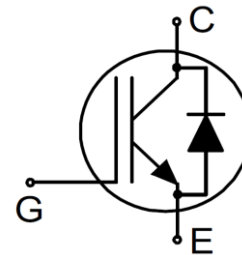
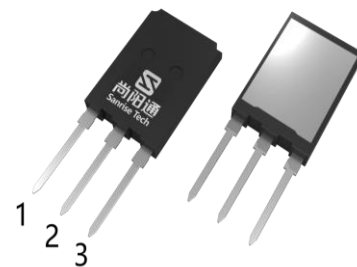


Figure 1 Symbol of SRE160N065FSUD8

Package Type



TO-247Plus

Pin 1- Gate

Pin 2&backside- Collector

Pin 3-Emitter

Figure 2 Package Type of SRE160N065FSUD8

Ordering Information

SRE160N065FSUD8 □ □ - □

Circuit Type _____
 Package _____
 TP: TO-247Plus

G: Green
 Blank: Tube
 TR: Tape & Reel

Package	Part Number	Marking ID	Packing Type
TO-247Plus	SRE160N065FSUD8TP-G1A	SRE160N065FSUD8TPG1A	Tube

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Collector-emitter voltage	V_{CES}	650	V
Gate-emitter Voltage	V_{GES}	± 20	V
Transient Gate-emitter Voltage		± 30	V
Continuous Collector Current	I_C	$T_C=25^\circ\text{C}$	240 ⁽¹⁾
		$T_C=100^\circ\text{C}$	160
Pulsed Collector Current, Limited by T_{Jmax}	I_{CM}	480	A
Diode Continuous Collector Current	I_F	$T_C=25^\circ\text{C}$	200
		$T_C=100^\circ\text{C}$	160
Diode Pulsed Current, Limited by T_{Jmax}	I_{FM}	420	A
Power Dissipation	P_{tot}	$T_C=25^\circ\text{C}$	882
		$T_C=100^\circ\text{C}$	441
Short Circuit withstand time: $V_{GE}=15\text{V}, V_{CC} \leq 400\text{V}, T_{j_start}=25^\circ\text{C};$ Allow number of short circuits < 1000; Time between short circuits: 1.0S;	tsc	8	us
Operating Junction Temperature Range	T_J	$-40 \sim 175^{(2)}$	$^\circ\text{C}$
Storage Temperature	T_{STG}	$-55 \sim 150$	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)	T_{LEAD}	260	$^\circ\text{C}$

Note:

- Limited to bondwire.
- Reliability testing conducted at $T_{Jmax}=175^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
IGBT thermal Resistance, Junction-to-Case	R_{thJC}	-	-	0.17	$^\circ\text{C}/\text{W}$
Diode thermal Resistance, Junction-to-Case	R_{thJC}	-	-	0.3	
Thermal Resistance, Junction-to-Ambient	R_{thJA}	-	-	40	

Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Statistic Characteristics							
Collector-emitter Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=250\mu A$	650			V	
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=1.6mA$	4.2	4.8	5.4	V	
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15V, I_C=160A,$ $T_J=25^\circ\text{C}$		1.46	1.60	V	
		$T_J=125^\circ\text{C}$		1.72		V	
		$T_J=175^\circ\text{C}$		1.89		V	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=650V, V_{GE}=0V$ $T_J=25^\circ\text{C}$		0.1	10	μA	
		$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Leakage Current	Forward	I_{GESF}	$V_{GE}=20V, V_{CE}=0V$			100	nA
	Reverse	I_{GESR}	$V_{GE}=-20V, V_{CE}=0V$			-100	nA
Dynamic Characteristics							
Input Capacitance	C_{IES}	$V_{CE}=25V, V_{GE}=0V,$ $f=100\text{KHz}$		8446		pF	
Output Capacitance	C_{OES}			585			
Reverse Transfer Capacitance	C_{RES}			113			
Gate Resistance	R_G	$f=1\text{MHz}, \text{Open Drain}$		0.5		Ω	
Turn-on Delay Time	$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=400V, I_C=160A$ $R_G=20\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		98		ns	
Rise Time	t_r			132		ns	
Turn-off Delay Time	$t_{d(off)}$			560		ns	
Fall Time	t_f			96		ns	
Turn-on energy	E_{on}			9.0		mJ	
Turn-off energy	E_{off}			5.0		mJ	
Total switching energy	E_{ts}			14.0		mJ	
Turn-on Delay Time	$t_{d(on)}$		$T_J=150^\circ\text{C}$ $V_{CC}=400V, I_C=160A$ $R_G=20\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		92		ns
Rise Time	t_r				137		ns
Turn-off Delay Time	$t_{d(off)}$				665		ns
Fall Time	t_f			125		ns	
Turn-on energy	E_{on}			10.4		mJ	
Turn-off energy	E_{off}			6		mJ	
Total switching energy	E_{ts}			16.4		mJ	
Gate to Emitter Charge	Q_{GE}	$V_{CC}=400V, I_C=160A$ $V_{GE}=0 \text{ to } 15V$			87		nC
Gate to Collector Charge	Q_{GC}			124			
Gate Charge Total	Q_G			356			

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Reverse Diode Characteristics						
Diode Forward Voltage	V_F	$I_F=80A$ $T_J=25^\circ C$	1.10	1.50	1.90	V
		$I_F=80A$ $T_J=125^\circ C$		1.36		
		$I_F=80A$ $T_J=175^\circ C$		1.27		
		$I_F=160A$ $T_J=25^\circ C$	1.30	1.78	2.20	V
		$I_F=160A$ $T_J=125^\circ C$		1.71		
		$I_F=160A$ $T_J=175^\circ C$		1.66		
Reverse Recovery Time	t_{rr}	$T_J=25^\circ C$ $V_R=400V, I_F=80A$ $R_G=20\Omega$ $dI_F/dt=730A/\mu s$		182		ns
Reverse Recovery Charge	Q_{rr}			1.65		μC
Peak Reverse Recovery Current	I_{rrm}			26		A
Diode peak rate of fall off reverse recovery current	dI_{rr}/dt			-200		$A/\mu s$
Reverse recovery energy	E_{rec}			0.81		mJ
Reverse Recovery Time	t_{rr}	$T_J=175^\circ C$ $V_R=400V, I_F=80A$ $R_G=20\Omega$ $dI_F/dt=710A/\mu s$		404		ns
Reverse Recovery Charge	Q_{rr}			11.1		μC
Peak Reverse Recovery Current	I_{rrm}			59		A
Diode peak rate of fall off reverse recovery current	dI_{rr}/dt			-180		$A/\mu s$
Reverse recovery energy	E_{rec}			5.94		mJ
Reverse Recovery Time	t_{rr}	$T_J=25^\circ C$ $V_R=400V, I_F=160A$ $R_G=20\Omega$ $dI_F/dt=650A/\mu s$		197		ns
Reverse Recovery Charge	Q_{rr}			1.71		μC
Peak Reverse Recovery Current	I_{rrm}			26		A
Diode peak rate of fall off reverse recovery current	dI_{rr}/dt			-160		$A/\mu s$
Reverse recovery energy	E_{rec}			0.85		mJ
Reverse Recovery Time	t_{rr}	$T_J=175^\circ C$ $V_R=400V, I_F=160A$ $R_G=20\Omega$ $dI_F/dt=670A/\mu s$		463		ns
Reverse Recovery Charge	Q_{rr}			14.6		μC
Peak Reverse Recovery Current	I_{rrm}			69		A
Diode peak rate of fall off reverse recovery current	dI_{rr}/dt			-190		$A/\mu s$
Reverse recovery energy	E_{rec}			8.11		mJ

Typical Performance Characteristics

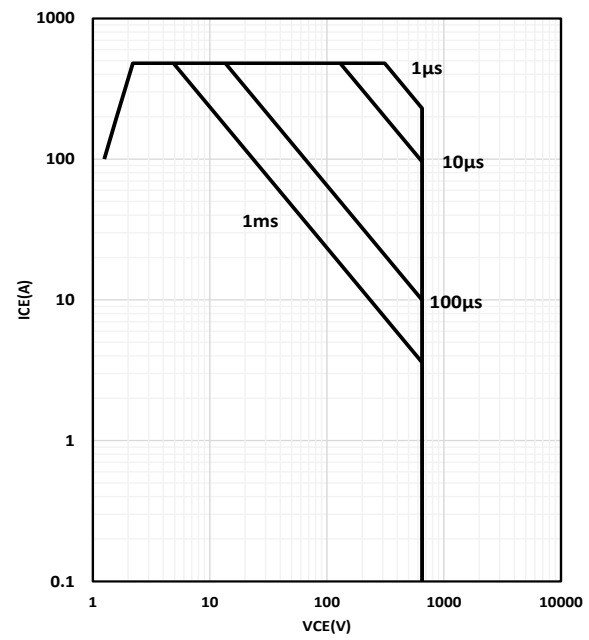
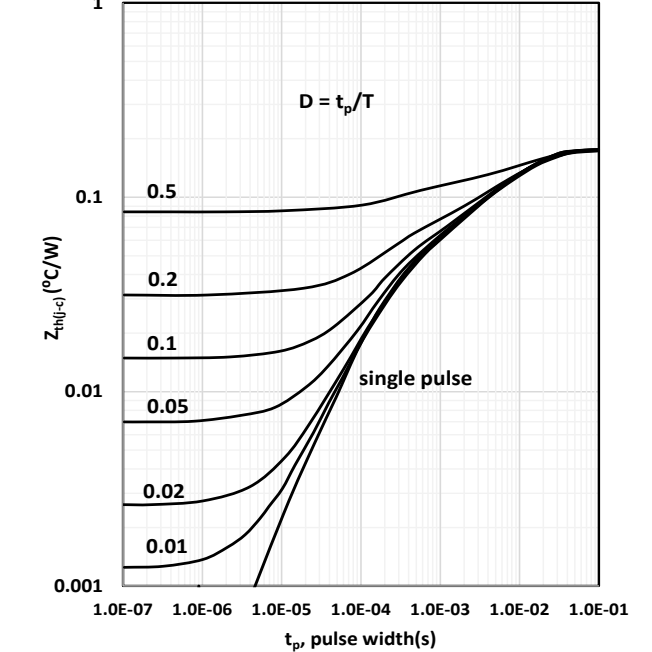
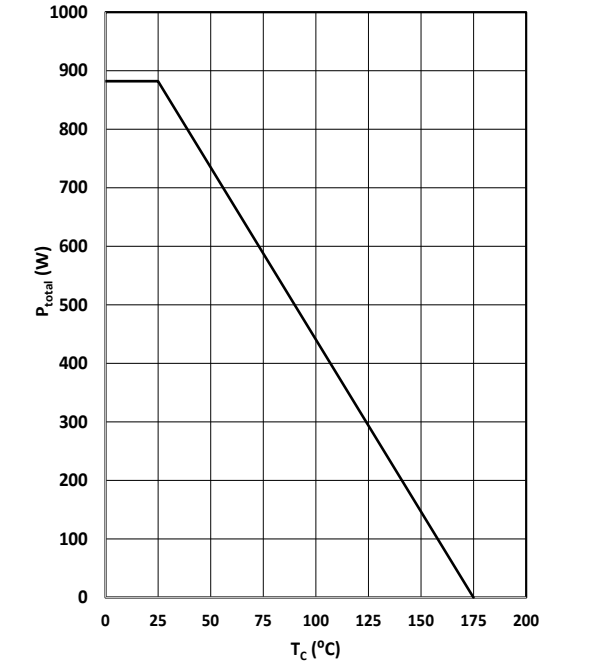
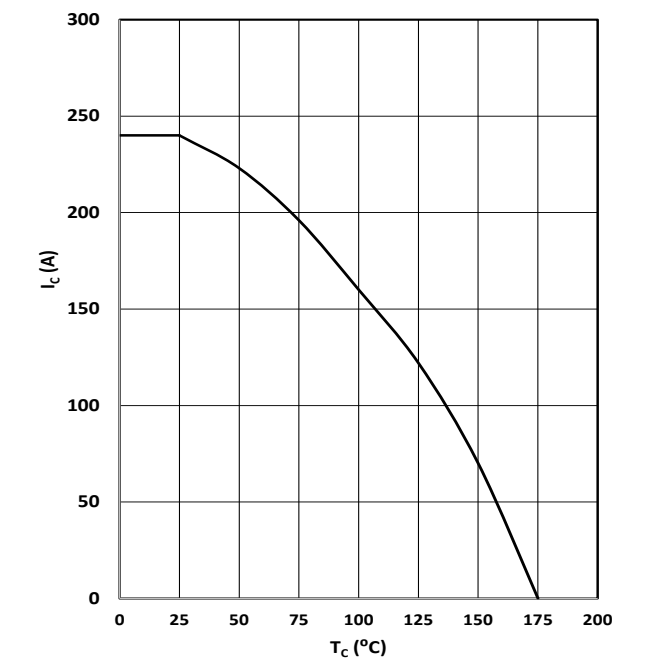
<p>Figure 3: IGBT forward bias safe operating area (FBSOA)</p>  <p>$I_C = f(V_{CE}); V_{GE} \geq 15/0V; T_j \leq 175^\circ C$</p>	<p>Figure 4: IGBT transient thermal impedance</p>  <p>$R_{th(j-c)} = f(t_p); \text{duty cycle: } D = t_p/T$</p>
<p>Figure 5: Power Dissipation</p>  <p>$P_{tot} = f(T_c)$</p>	<p>Figure 6: Collector current vs. temperature</p>  <p>$I_c = f(T_j); V_{GE} \geq 15/0V; T_j \leq 175^\circ C$</p>

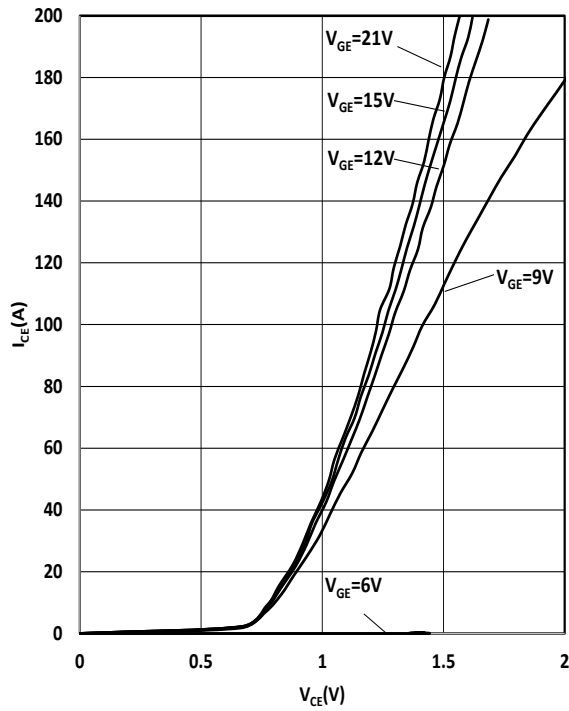
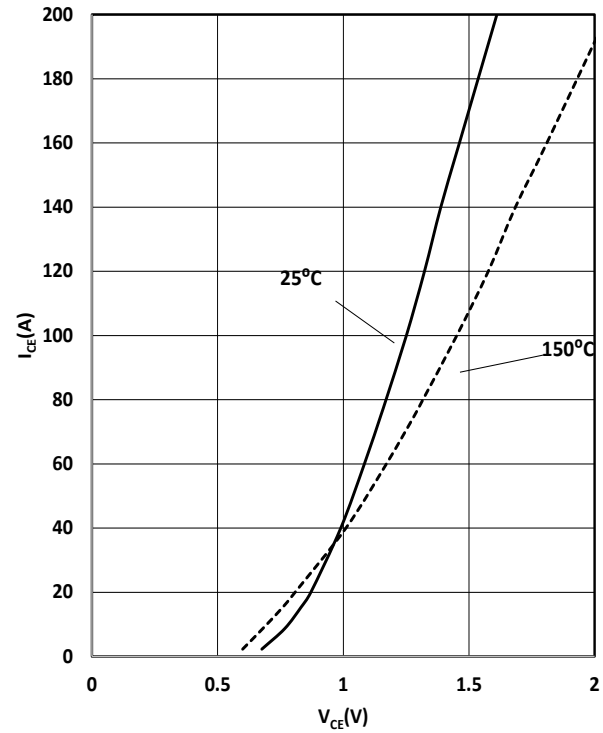
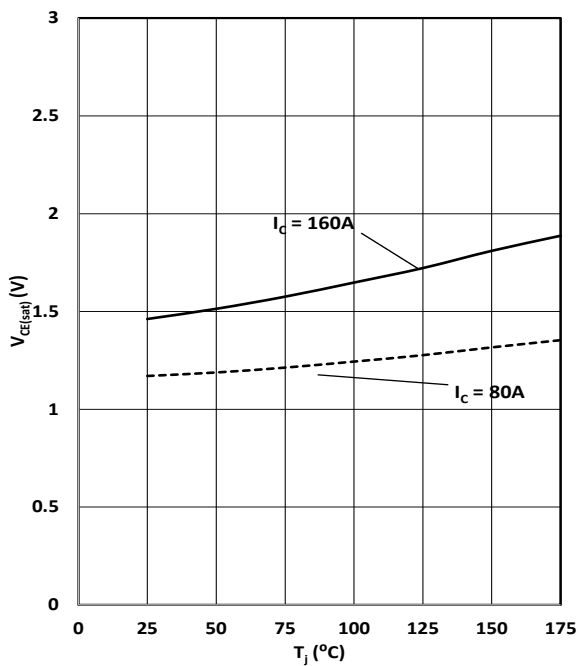
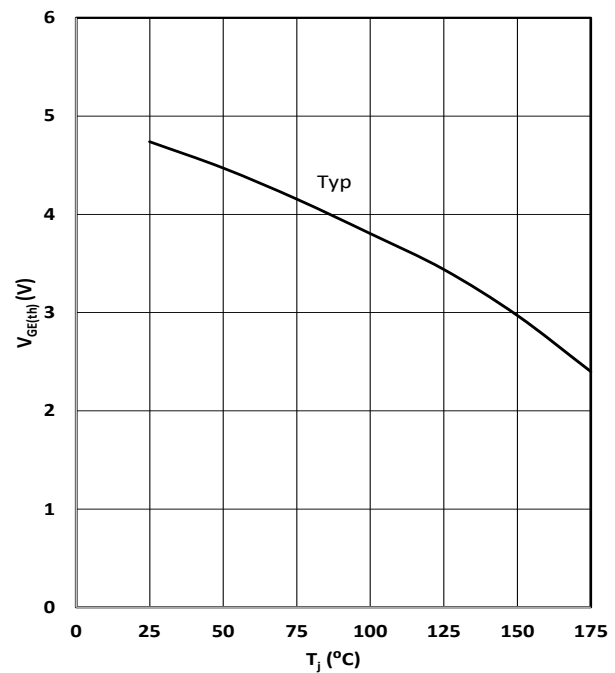
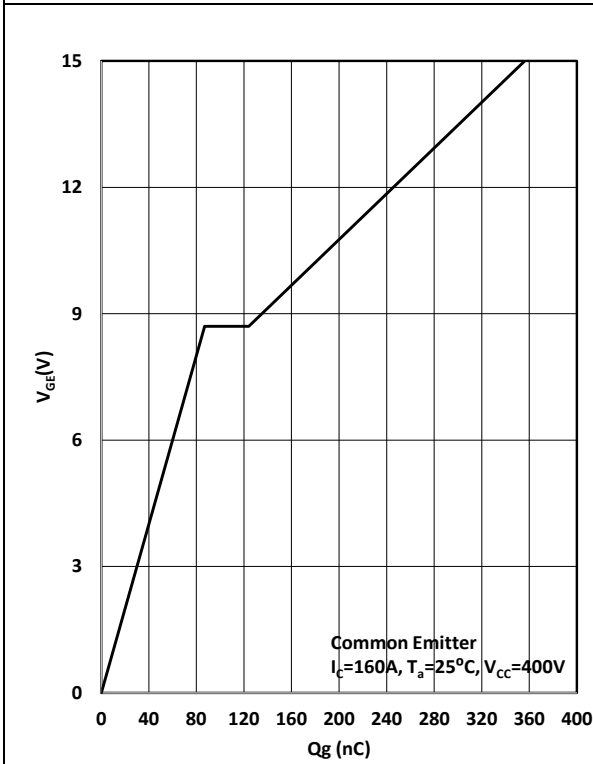
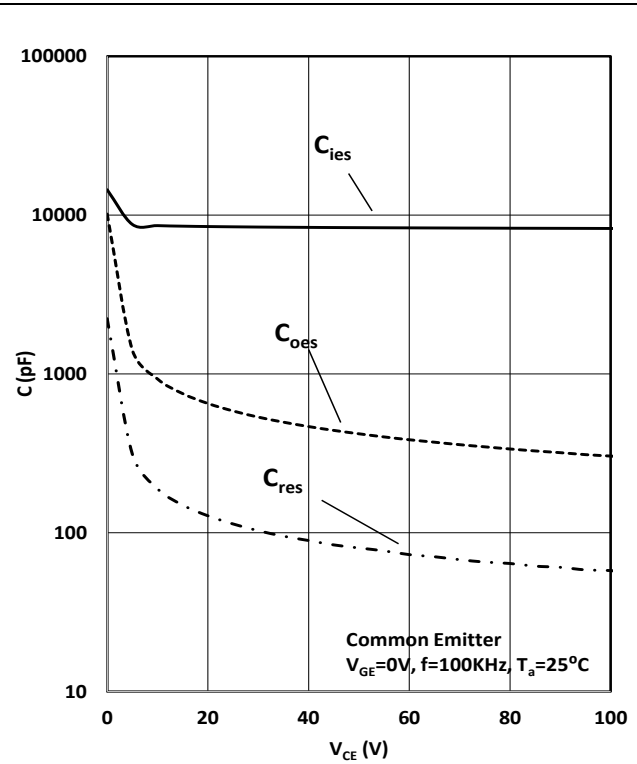
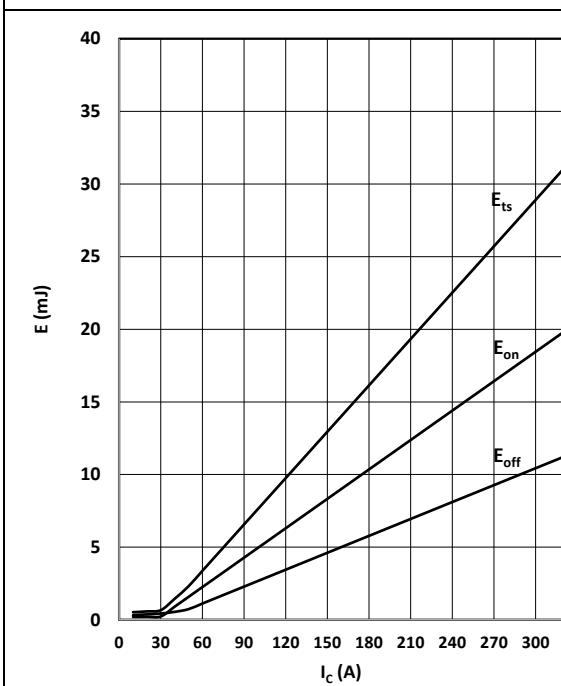
Figure 7: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 8: Typical transfer characteristic

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C vs } 150^\circ\text{C } V_{GE} = 15\text{V};$
Figure 9: Typical collector-emitter saturation voltage as a function of junction temperature

 $V_{CE} = f(T_j); V_{GE} = 15\text{V}$
Figure 10: Gate-emitter threshold voltage as a function of junction temperature

 $V_{GE} = f(T_j); I_{CE} = 1.6\text{mA}$

Figure 11: Typical Gate Charge


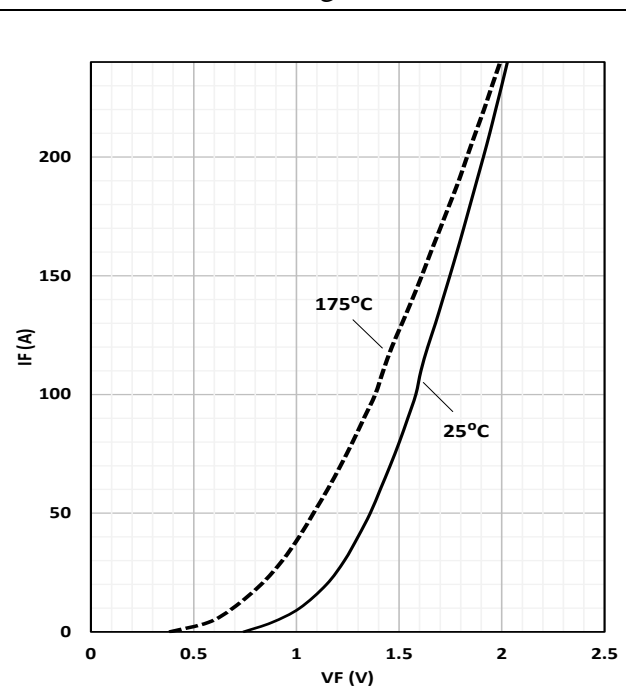
$$V_{GE} = f(Q_{gate}), I_C = 160A$$

Figure 12: Typical Capacitances


$$C = f(V_{CE}); V_{GE}=0; f=100KHz$$

Figure 13: Typical switching energy losses as a function of collector current


$$E = f(I_C); V_{CE}=400V; T_c=25^\circ C; R_G=20\Omega$$

Figure 14: Typical diode forward current as a function of forward voltage


$$I_F = f(V_F);$$

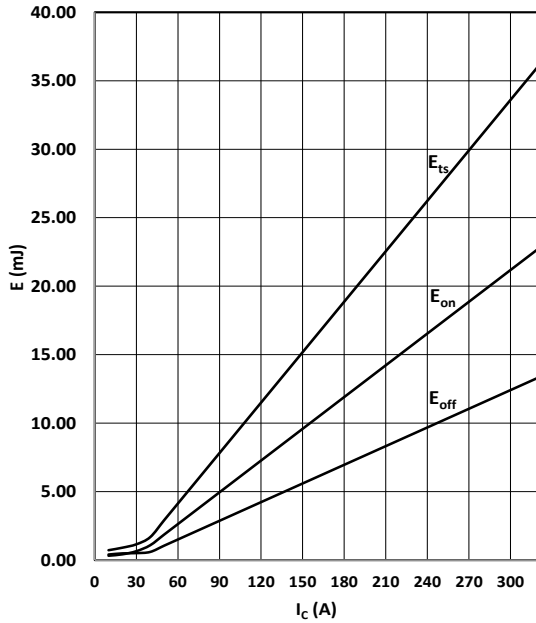
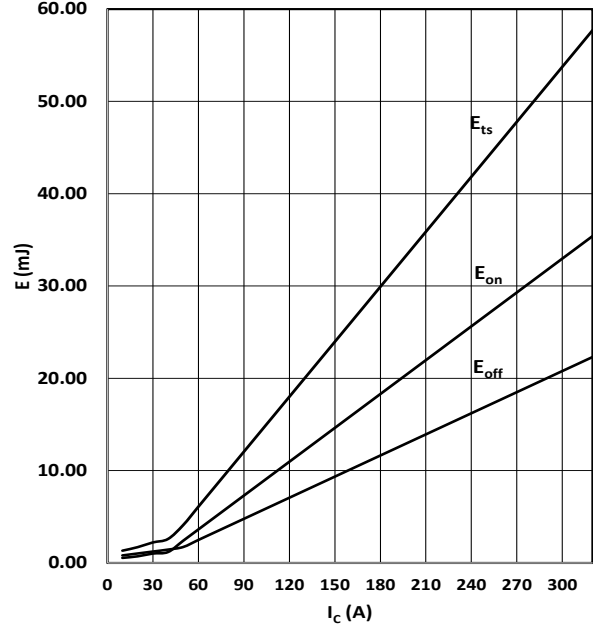
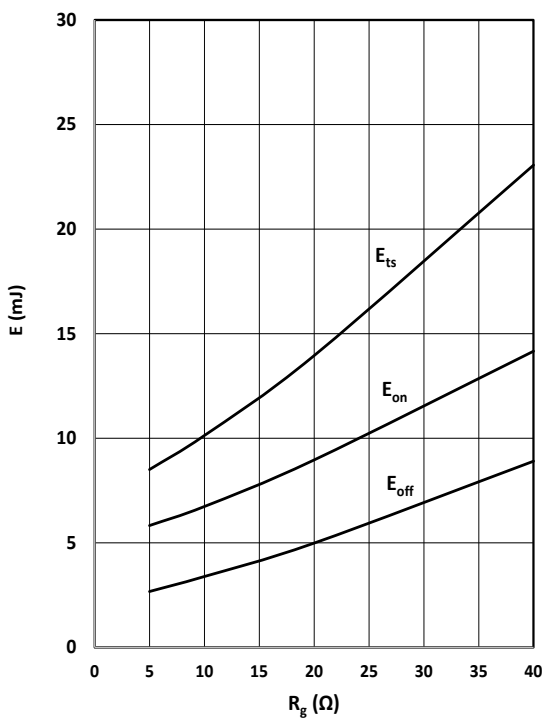
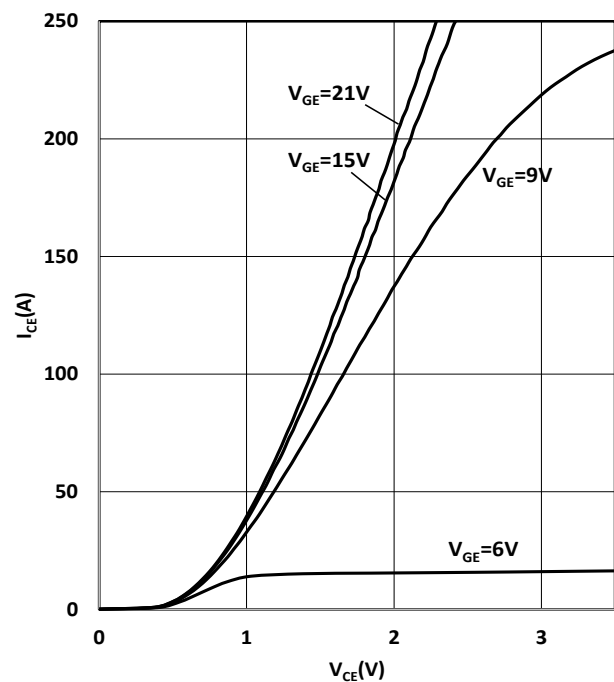
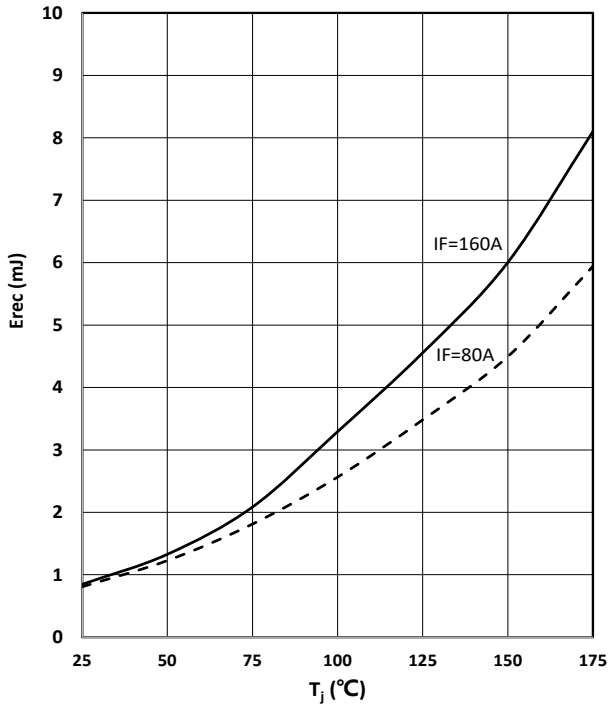
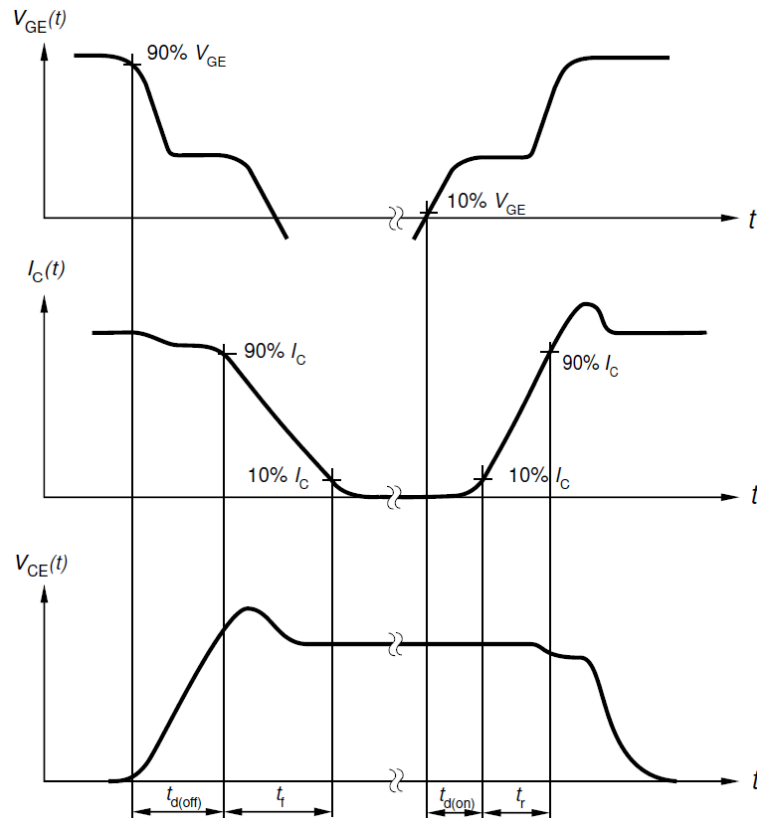
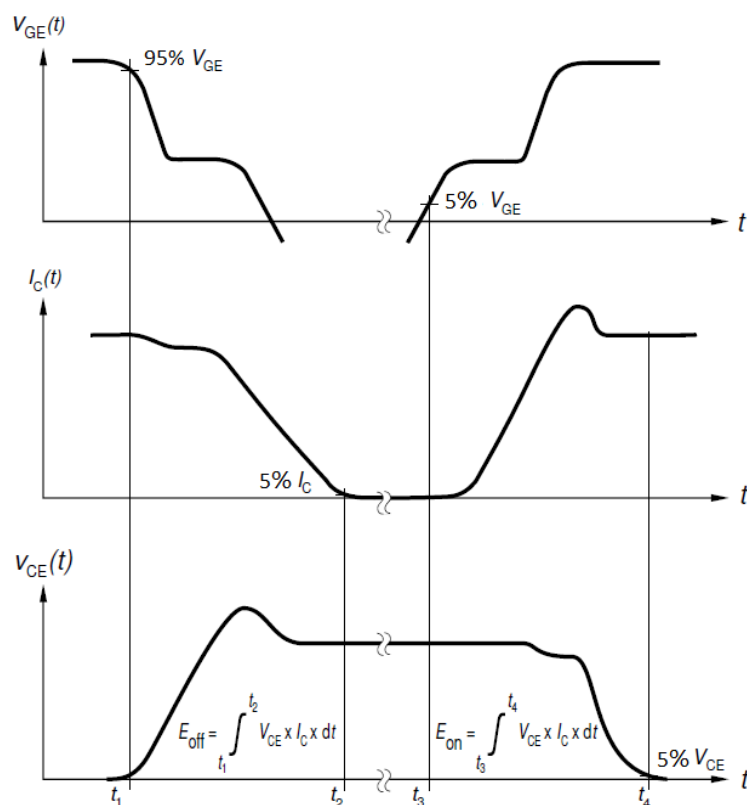
Figure15: Typical switching energy losses as a function of collector current

 $E=f(I_c); V_{CE}=400V; T_c=150^{\circ}C; R_g=20\Omega$
Figure 16: Typical switching energy losses as a function of collector current

 $E=f(I_c); V_{CE}=400V; T_c=150^{\circ}C; R_g=40\Omega$
Figure17: Typical switching energy losses as a function of gate resistor

 $E=f(I_c); V_{CE}=400V; T_c=25^{\circ}C; I_c=160A$
Figure18: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 150^{\circ}C; \text{parameter: } V_{GE}$

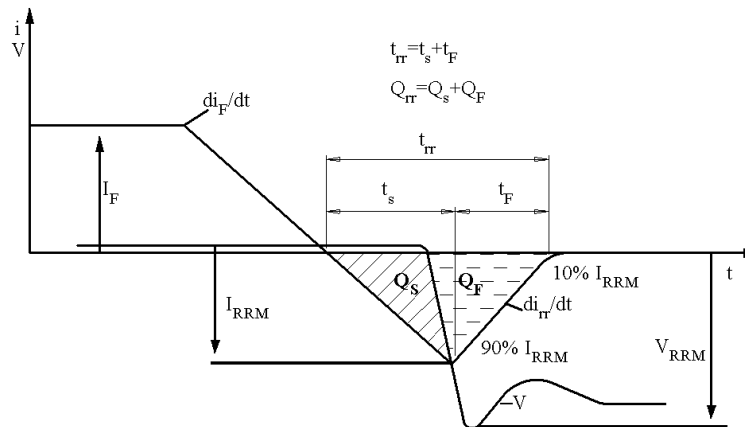
Figure19: Typical reverse energy losses as a function of junction temperature



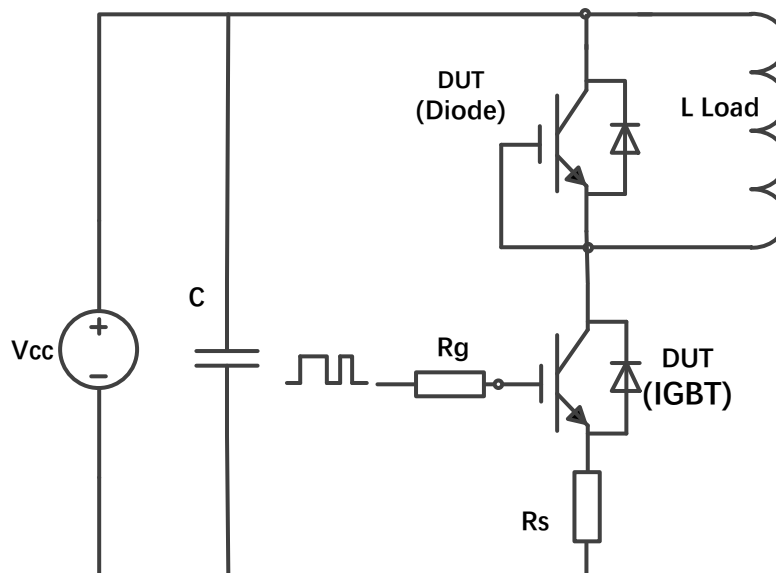
$E_{rec} = f(T_j)$; $V_{CE}=400V$; $I_F=80A$ 160A; $R_G=20\Omega$

Test Circuits
1. Definition Switching times

2. Definition Switching losses


3. Definition Diode Switching Characteristics



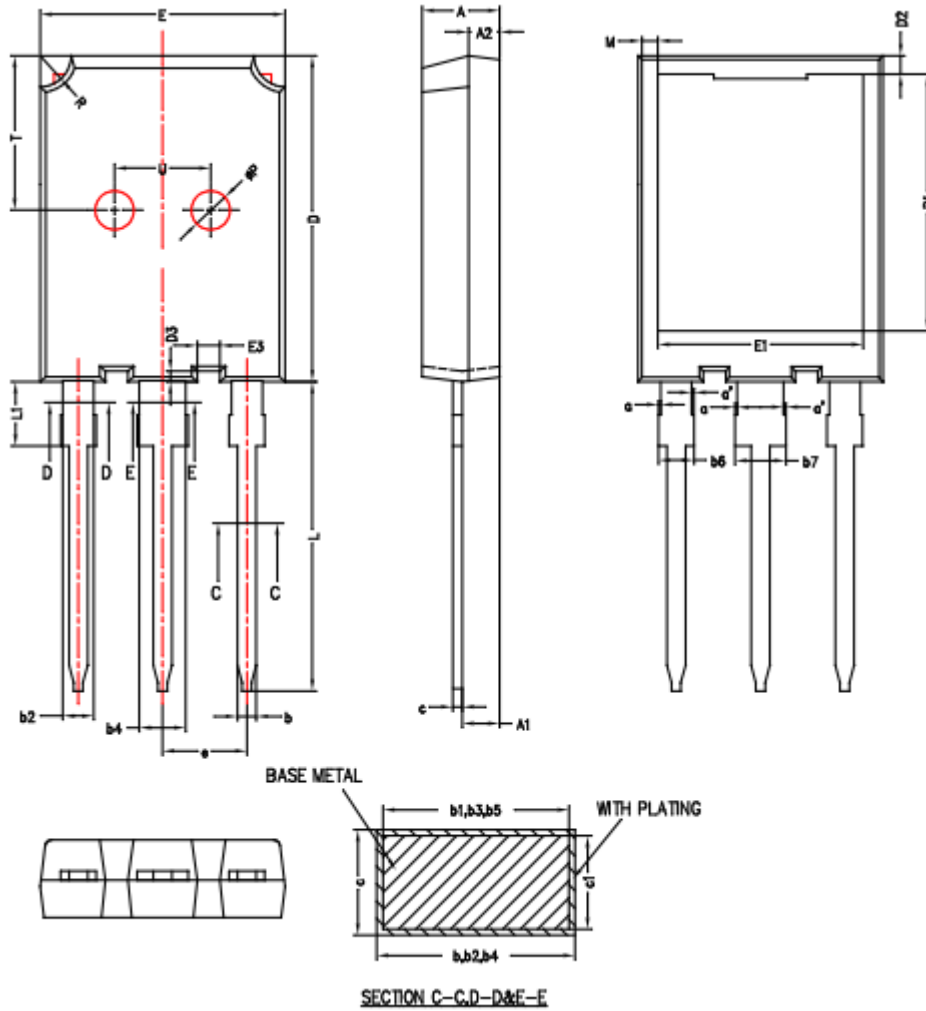
4. Dynamic test circuit



Mechanical Dimensions

TO-247 Plus

Unit: mm



160A 650V Trench Fieldstop IGBT with FRD
SRE160N065FSUD8

Symbol [↵]	Dimensions (mm) [↵]			Symbol [↵]	Dimensions (mm) [↵]		
	Min. [↵]	Typ. [↵]	Max. [↵]		Min. [↵]	Typ. [↵]	Max. [↵]
A [↵]	4.90 [↵]	5.00 [↵]	5.10 [↵]	D [↵]	20.90 [↵]	21.00 [↵]	21.10 [↵]
A1 [↵]	2.31 [↵]	2.41 [↵]	2.51 [↵]	D1 [↵]	16.25 [↵]	16.55 [↵]	16.85 [↵]
A2 [↵]	1.90 [↵]	2.00 [↵]	2.10 [↵]	D2 [↵]	1.05 [↵]	1.17 [↵]	1.35 [↵]
a [↵]	0 [↵]	- [↵]	0.15 [↵]	D3 [↵]	0.58 [↵]	0.68 [↵]	0.78 [↵]
a' [↵]	0 [↵]	- [↵]	0.15 [↵]	E [↵]	15.70 [↵]	15.80 [↵]	15.90 [↵]
b [↵]	1.16 [↵]	- [↵]	1.26 [↵]	E1 [↵]	13.10 [↵]	13.26 [↵]	13.50 [↵]
b1 [↵]	1.15 [↵]	1.20 [↵]	1.22 [↵]	E3 [↵]	1.35 [↵]	1.45 [↵]	1.55 [↵]
b2 [↵]	1.96 [↵]	- [↵]	2.06 [↵]	e [↵]	5.34 [↵]	5.44 [↵]	5.54 [↵]
b3 [↵]	1.95 [↵]	2.00 [↵]	2.02 [↵]	L [↵]	19.80 [↵]	19.92 [↵]	20.10 [↵]
b4 [↵]	2.96 [↵]	- [↵]	3.06 [↵]	L1 [↵]	3.90 [↵]	- [↵]	4.30 [↵]
b5 [↵]	2.95 [↵]	3.00 [↵]	3.02 [↵]	M [↵]	0.70 [↵]	- [↵]	1.30 [↵]
b6 [↵]	- [↵]	- [↵]	2.25 [↵]	P [↵]	2.40 [↵]	2.50 [↵]	2.60 [↵]
b7 [↵]	- [↵]	- [↵]	3.25 [↵]	R [↵]	1.90 [↵]	2.00 [↵]	2.10 [↵]
c [↵]	0.59 [↵]	- [↵]	0.66 [↵]	T [↵]	9.80 [↵]	- [↵]	10.20 [↵]
c1 [↵]	0.58 [↵]	0.60 [↵]	0.62 [↵]	U [↵]	6.00 [↵]	- [↵]	6.40 [↵]



Shenzhen Sanrise Technology Co., LTD.

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Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.
A1206, Skyworth building, No. 008, gaoxinnan 1st Road,
Gaoxin District, Yuehai street, Nanshan District, ShenZhen,
P.R. China
Tel: +86-755-22953335
Fax: +86-755-22916878

- Shanghai Office

Shenzhen Sanrise Technology Co., LTD.
Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China
Tel: +86-21-68825918